

351024
12/20/01

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10028880	FILING DATE 12/20/2001	CLASS 156	SUBCLASS 272.8	GALL 1732 1734	EXAMINER Kilkeug
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**APPLICANTS: Chuang Ta-Ko; Tanaka Sakae;

**CONTINUING DATA VERIFIED:

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** FOREIGN APPLICATIONS VERIFIED:

TAIWAN 90118342 07/26/2001

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no

35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

B-4442 619416-6

TITLE : Method for bonding an integrated circuit device to a glass substrate

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L/Rev. 12-94

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	Total Claims Print Claims No. O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Primary Examiner	Sheets Drawn Figs. Drawn Print Figs.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner
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